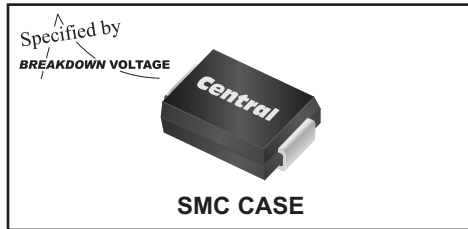


1.5SMC6.8CA
THRU
1.5SMC220CA

SURFACE MOUNT SILICON
BI-DIRECTIONAL
GLASS PASSIVATED JUNCTION
TRANSIENT VOLTAGE SUPPRESSORS
1500 WATT, 6.8 THRU 220 VOLT



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR 1.5SMC6.8CA series devices are surface mount bi-directional glass passivated junction Transient Voltage Suppressors designed to protect voltage sensitive components from high voltage transients.

THIS DEVICE IS MANUFACTURED WITH A GLASS PASSIVATED CHIP FOR OPTIMUM RELIABILITY.

Note: For uni-directional devices, please refer to the 1.5SMC6.8A series data sheet.

MARKING CODE: SEE ELECTRICAL CHARACTERISTICS TABLE

MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$ unless otherwise noted)

Peak Power Dissipation (Note 1)

Operating and Storage Junction Temperature

SYMBOL

P_{PK} 1500
 T_J, T_{stg} -65 to +150

UNITS

W
 $^\circ\text{C}$

ELECTRICAL CHARACTERISTICS: ($T_A=25^\circ\text{C}$ unless otherwise noted)

TYPE	BREAKDOWN VOLTAGE $V_{BR} @ I_T$			TEST CURRENT I_T	WORKING PEAK REVERSE VOLTAGE V_{RWM}	MAXIMUM REVERSE LEAKAGE CURRENT $I_R @ V_{RWM}$	MAXIMUM CLAMPING VOLTAGE $V_C @ I_{PP}$	PEAK PULSE CURRENT (Note 1) I_{PP}	MAXIMUM TEMPERATURE COEFFICIENT θV_{BR}	MARKING CODE
	MIN V	NOM V	MAX V							
1.5SMC6.8CA	6.45	6.8	7.14	10	5.8	2000	10.5	143	0.057	C6V8C
1.5SMC7.5CA	7.13	7.5	7.88	10	6.4	1000	11.3	132	0.061	C7V5C
1.5SMC8.2CA	7.79	8.2	8.61	10	7.02	400	12.1	124	0.065	C8V2C
1.5SMC9.1CA	8.65	9.1	9.55	1.0	7.78	100	13.4	112	0.068	C9V1C
1.5SMC10CA	9.5	10	10.5	1.0	8.55	20	14.5	103	0.073	C10C
1.5SMC11CA	10.5	11	11.6	1.0	9.4	5.0	15.6	96	0.075	C11C
1.5SMC12CA	11.4	12	12.6	1.0	10.2	5.0	16.7	90	0.078	C12C
1.5SMC13CA	12.4	13	13.7	1.0	11.1	5.0	18.2	82	0.081	C13C
1.5SMC15CA	14.3	15	15.8	1.0	12.8	5.0	21.2	71	0.084	C15C
1.5SMC16CA	15.2	16	16.8	1.0	13.6	5.0	22.5	67	0.086	C16C
1.5SMC18CA	17.1	18	18.9	1.0	15.3	5.0	25.2	59.5	0.088	C18C
1.5SMC20CA	19.0	20	21.0	1.0	17.1	5.0	27.7	54	0.090	C20C
1.5SMC22CA	20.9	22	23.1	1.0	18.8	5.0	30.6	49	0.092	C22C
1.5SMC24CA	22.8	24	25.2	1.0	20.5	5.0	33.2	45	0.094	C24C
1.5SMC27CA	25.7	27	28.4	1.0	23.1	5.0	37.5	40	0.096	C27C
1.5SMC30CA	28.5	30	31.5	1.0	25.6	5.0	41.4	36	0.097	C30C
1.5SMC33CA	31.4	33	34.7	1.0	28.2	5.0	45.7	33	0.098	C33C
1.5SMC36CA	34.2	36	37.8	1.0	30.8	5.0	49.9	30	0.099	C36C
1.5SMC39CA	37.1	39	41	1.0	33.3	5.0	53.9	28	0.100	C39C

Note 1: Non-repetitive 10x1,000 μs pulse.

R10 (15-August 2019)

**1.5SMC6.8CA
THRU
1.5SMC220CA**

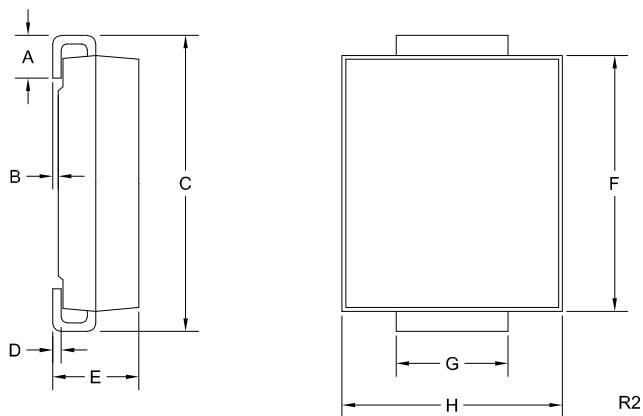
**SURFACE MOUNT SILICON
BI-DIRECTIONAL
GLASS PASSIVATED JUNCTION
TRANSIENT VOLTAGE SUPPRESSORS
1500 WATT, 6.8 THRU 220 VOLT**



ELECTRICAL CHARACTERISTICS - Continued: (T_A=25°C unless otherwise noted)

TYPE	BREAKDOWN VOLTAGE $V_{BR} @ I_T$			TEST CURRENT I_T	WORKING PEAK REVERSE VOLTAGE V_{RWM}	MAXIMUM REVERSE LEAKAGE CURRENT $I_R @ V_{RWM}$	MAXIMUM CLAMPING VOLTAGE $V_C @ I_{PP}$	PEAK PULSE CURRENT (Note 1) I_{PP}	MAXIMUM TEMPERATURE COEFFICIENT ΘV_{BR}	MARKING CODE
	MIN V	NOM V	MAX V							
1.5SMC43CA	40.9	43	45.2	1.0	36.8	5.0	59.3	25.3	0.101	C43C
1.5SMC47CA	44.7	47	49.4	1.0	40.2	5.0	64.8	23.2	0.101	C47C
1.5SMC51CA	48.5	51	53.6	1.0	43.6	5.0	70.1	21.4	0.102	C51C
1.5SMC56CA	53.2	56	58.8	1.0	47.8	5.0	77	19.5	0.103	C56C
1.5SMC62CA	58.9	62	65.1	1.0	53.0	5.0	85	17.7	0.104	C62C
1.5SMC68CA	64.6	68	71.4	1.0	58.1	5.0	92	16.3	0.104	C68C
1.5SMC75CA	71.3	75	78.8	1.0	64.1	5.0	103	14.6	0.105	C75C
1.5SMC82CA	77.9	82	86.1	1.0	70.1	5.0	113	13.3	0.105	C82C
1.5SMC91CA	86.5	91	95.5	1.0	77.8	5.0	125	12	0.106	C91C
1.5SMC100CA	95.0	100	105	1.0	85.5	5.0	137	11	0.106	C100C
1.5SMC110CA	104.5	110	115.5	1.0	94.0	5.0	152	9.9	0.107	C110C
1.5SMC120CA	114	120	126	1.0	102	5.0	165	9.1	0.107	C120C
1.5SMC130CA	123.5	130	136.5	1.0	111	5.0	179	8.4	0.107	C130C
1.5SMC150CA	142.5	150	157.5	1.0	128	5.0	207	7.2	0.108	C150C
1.5SMC160CA	152	160	168	1.0	136	5.0	219	6.8	0.108	C160C
1.5SMC170CA	161.5	170	178.5	1.0	145	5.0	234	6.4	0.108	C170C
1.5SMC180CA	171	180	189	1.0	154	5.0	246	6.1	0.108	C180C
1.5SMC200CA	190	200	210	1.0	171	5.0	274	5.5	0.108	C200C
1.5SMC220CA	209	220	231	1.0	185	5.0	328	4.6	0.108	C220C

SMC CASE - MECHANICAL OUTLINE



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.030	0.060	0.76	1.52
B	0.002	0.008	0.05	0.20
C	0.305	0.320	7.75	8.13
D	0.006	0.012	0.15	0.31
E	0.079	0.103	2.00	2.62
F	0.260	0.280	6.60	7.11
G	0.108	0.128	2.75	3.25
H	0.220	0.245	5.59	6.22

SMC (REV: R2)

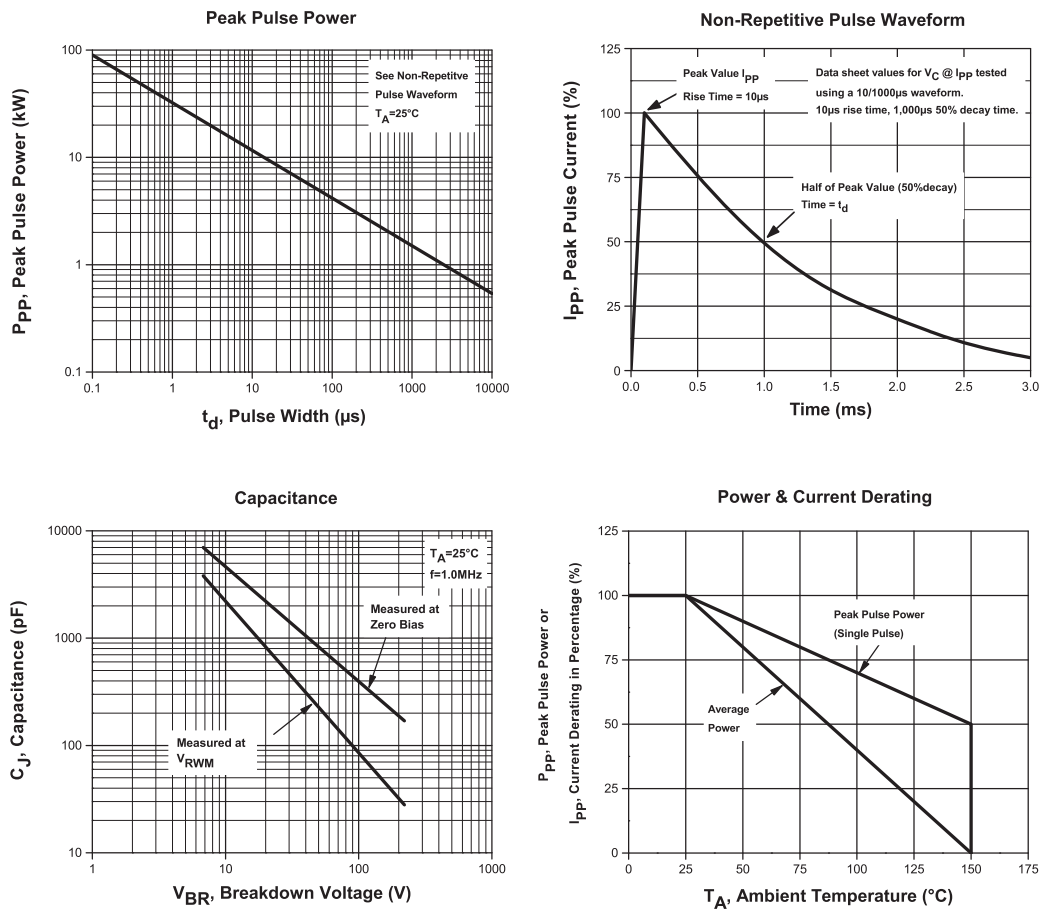
R10 (15-August 2019)

1.5SMC6.8CA
THRU
1.5SMC220CA

SURFACE MOUNT SILICON
BI-DIRECTIONAL
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1500 WATT, 6.8 THRU 220 VOLT



TYPICAL ELECTRICAL CHARACTERISTICS

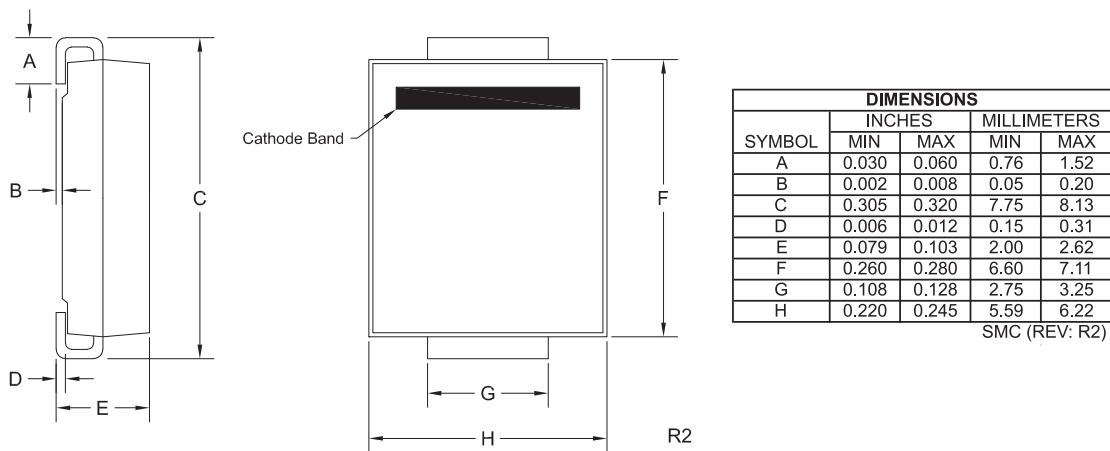


R10 (15-August 2019)

Package Details
SMC Case



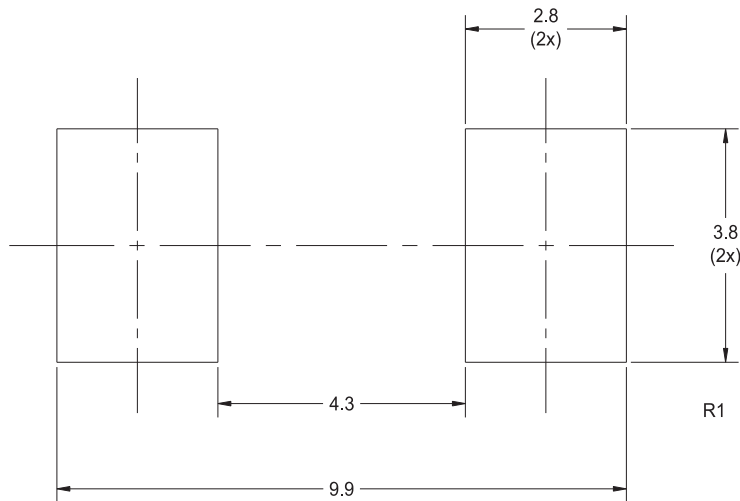
Mechanical Drawing



Lead Code:
Reference individual
device datasheet.

Part Marking: 3-6 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



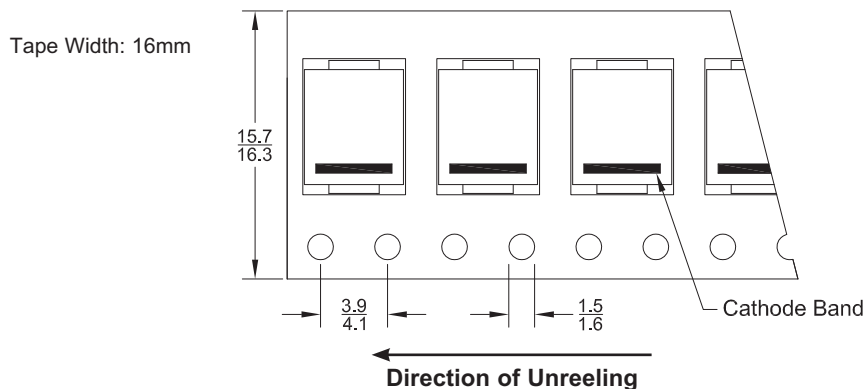
R4 (18-February 2021)

Package Details

SMC Case



Tape Dimensions and Orientation (Dimensions in mm)



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-D

Packaging Base

13" Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code and Ship Date.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
13"	4	12,000	15x4x15	38x10x38	12	6
	11	33,000	15x15x9	38x38x23	30	14
	24	72,000	15x15x18	38x38x46	64	29

Ordering Information

- For devices taped and reeled on 13" reels, add TR13 suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R4 (18-February 2021)

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Material Composition Specification

SMC Case



Device average mass 232.5 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.63%	3.8	Si	7440-21-3	1.63%	3.8	16,344
leadframe	copper	39.11%	90.92	Cu	7440-50-8	39.11%	90.92	391,054
die attach	high temperature solder paste	1.88%	4.36	Pb	7439-92-1	1.73%	4.033	17,346
				Sn	7440-31-5	0.09%	0.218	938
				Ag	7440-22-4	0.05%	0.109	469
encapsulation*	EMC	56.77%	132	silica	7631-86-9	38.61%	89.76	386,065
				epoxy resin	29690-82-2	11.35%	26.4	113,548
				phenol resin	9003-35-4	5.68%	13.2	56,774
				Sb ₂ O ₃	1309-64-4	0.57%	1.32	5,677
				Br	7726-95-6	0.57%	1.32	5,677
	EMC GREEN	56.77%	132	silica (fused)	60676-86-0	43.72%	101.64	437,161
				epoxy resin	29690-82-2	5.68%	13.2	56,774
				phenol resin	9003-35-4	5.51%	12.804	55,071
				carbon black	1333-86-4	0.17%	0.396	1,703
				metal hydroxide	1309-42-8	1.7%	3.96	17,032
plating**	tin/lead process	0.61%	1.42	Sn	7440-31-5	0.49%	1.136	4,886
				Pb	7439-92-1	0.12%	0.284	1,222
	matte tin	0.61%	1.42	Sn	7440-31-5	0.61%	1.42	6,108

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix "PB FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R6 (16-July 2018)

www.centalsemi.com

Material Composition Specification

SMC Case



Device average mass 232.5 mg
Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.63%	3.8	Si	7440-21-3	1.63%	3.8	16,344
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				Br	7726-95-6	0.57%	1.32	5,677
	EMC GREEN	56.77%	132	silica (fused)	60676-86-0	43.72%	101.64	437,161
				epoxy resin	29690-82-2	5.68%	13.2	56,774
				phenol resin	9003-35-4	5.51%	12.804	55,071
				carbon black	1333-86-4	0.17%	0.396	1,703
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R6 (16-July 2018)

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